

SOT1032-3

plastic thermal enhanced very thin quad flat package; no leads; 108 terminals; low stand-off height; UTLP based; body 8 x 8 x 0.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN108U
Package type industry code	HVQFN108U
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	U (UTLP based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	17-10-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.95	-	8	8.05	mm
E	package width	7.95	-	8	8.05	mm
A	seated height	0.85	-	0.9	1	mm
n ₂	actual quantity of termination	-	-	108	-	



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2. Package outline

HVQFN108U: plastic thermal enhanced very thin quad flat package; no leads; 108 terminals; low stand-off height; UTLP based; body 8 x 8 x 0.9 mm

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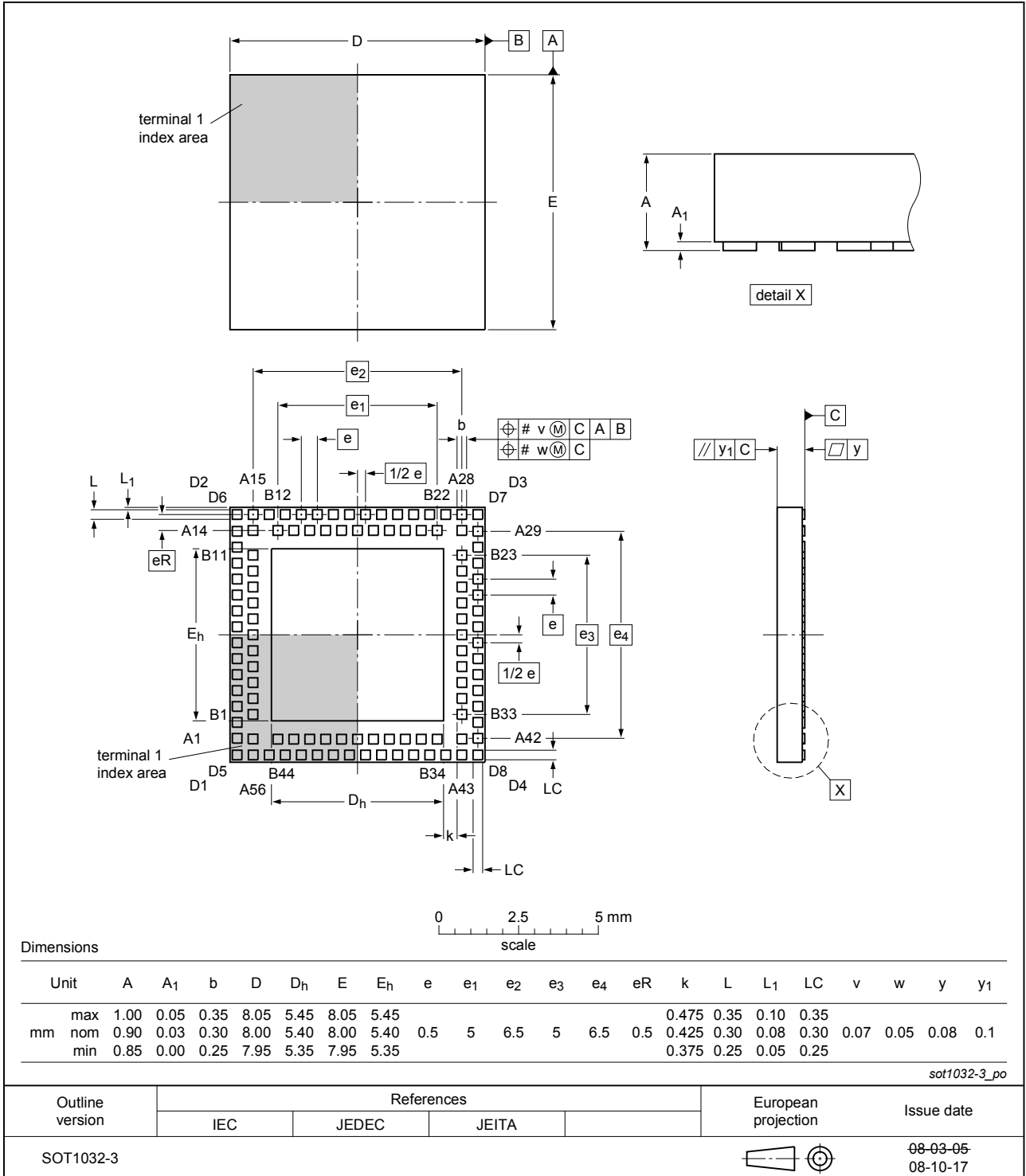


Fig. 1. Package outline HVQFN108U (SOT1032-3)

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3. Legal information

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